

Vishay Siliconix

# Automotive Dual N-Channel 30 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY	PRODUCT SUMMARY			
V <sub>DS</sub> (V)	30			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.0166			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.0276			
I <sub>D</sub> (A) per leg	8			
Configuration	Dual			
Package	PowerPAK SO-8L			

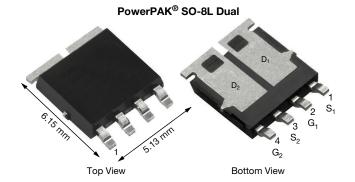
### **FEATURES**

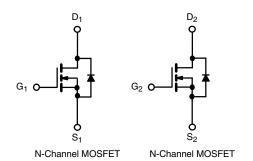
- TrenchFET® power MOSFET
- AEC-Q101 qualified
- 100 % Rq and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912





ROHS COMPLIANT HALOGEN FREE





<b>ABSOLUTE MAXIMUM RATINGS</b>	$T_C = 25  ^{\circ}C$ , unless	s otherwise noted	d)			
PARAMETER		SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		V <sub>DS</sub>	30			
Gate-Source Voltage		$V_{GS}$	± 20	V		
Continuous Drain Current a	T <sub>C</sub> = 25 °C	1	8			
Continuous Drain Current "	T <sub>C</sub> = 125 °C	I <sub>D</sub>	8			
Continuous Source Current (Diode Conduction	on) <sup>a</sup>	I <sub>S</sub>	8	Α		
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	32			
Single Pulse Avalanche Current		I <sub>AS</sub>	23			
Single Pulse Avalanche Energy  L = 0.1 mH		E <sub>AS</sub>	26	mJ		
Maximum Dower Dissipation b	T <sub>C</sub> = 25 °C	D	48	W		
Maximum Power Dissipation <sup>b</sup>	T <sub>C</sub> = 125 °C	$P_{D}$	16			
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C		
Soldering Recommendations (Peak Temperature) d, e			260	°C		

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient	PCB Mount c	R <sub>thJA</sub>	85	°C/W
Junction-to-Case (Drain)		R <sub>thJC</sub>	3.1	C/VV

#### **Notes**

- a. Package limited.
- b. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- c. When mounted on 1" square PCB (FR4 material).
- d. See solder profile (<a href="https://www.vishay.com/doc?73257">www.vishay.com/doc?73257</a>). The PowerPAK SO-8L is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.



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PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static				1			
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub>	= 0, I <sub>D</sub> = 250 μA	30	-	-	V
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu A$		1.5	2.0	2.5	V
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>DS</sub> =	0 V, V <sub>GS</sub> = ± 20 V	-	-	± 100	nA
		$V_{GS} = 0 V$	V <sub>DS</sub> = 30 V	-	-	1	μΑ
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{GS} = 0 V$	V <sub>DS</sub> = 30 V, T <sub>J</sub> = 125 °C	-	-	50	
		$V_{GS} = 0 V$	$V_{DS} = 30 \text{ V}, T_{J} = 175 ^{\circ}\text{C}$	-	-	150	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	$V_{DS} \ge 5 V$	30	-	ı	Α
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 7.6 A	-	0.0138	0.0166	Ω
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}$	I <sub>D</sub> = 5.9 A	-	0.0230	0.0276	
	1 (DS(OII)	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 7.6 A, T <sub>J</sub> = 125 °C	-	-	0.0252	
		V <sub>GS</sub> = 10 V	$I_D = 7.6 \text{ A}, T_J = 175 \text{ °C}$	-	-	0.0300	
Forward Transconductance b	9 <sub>fs</sub>	V <sub>DS</sub> :	-	20	-	S	
Dynamic <sup>b</sup>			T	•	1		
Input Capacitance	C <sub>iss</sub>			-	929	1161	
Output Capacitance	Coss	$V_{GS} = 0 V$	V <sub>DS</sub> = 15 V, f = 1 MHz	-	280	350	pF
Reverse Transfer Capacitance	C <sub>rss</sub>			-	93	116	
Total Gate Charge <sup>c</sup>	Qg			-	17	26	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$V_{DS} = 15 \text{ V}, I_D = 10 \text{ A}$	-	3	-	nC
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			-	3	-	
Gate Resistance	$R_{g}$		f = 1 MHz		-	5	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>				4.5	7	
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 15 \text{ V}, \text{ R}_L = 15 \Omega$ $I_D \cong 1 \text{ A}, \text{ V}_{GEN} = 10 \text{ V}, \text{ R}_g = 6 \Omega$		-	10	15	ns
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			-	20	30	
Fall Time <sup>c</sup>	t <sub>f</sub>	1		-	7	10	
Source-Drain Diode Ratings and Chara	acteristics <sup>b</sup>	•					
Pulsed Current <sup>a</sup>	I <sub>SM</sub>			-	-	32	Α

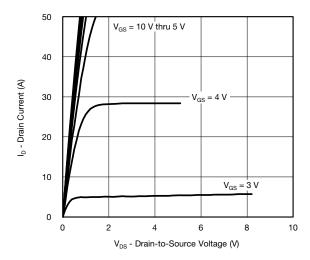
### Notes

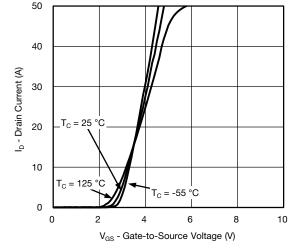
- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



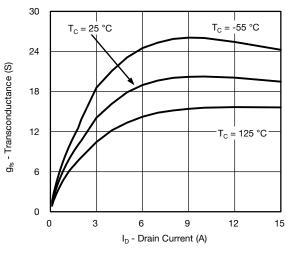
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)

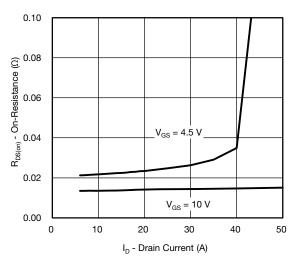




#### **Output Characteristics**

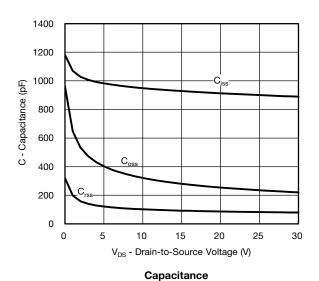


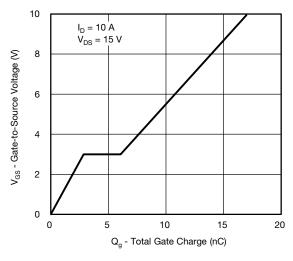




## Transconductance

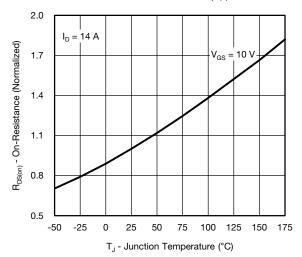
On-Resistance vs. Drain Current



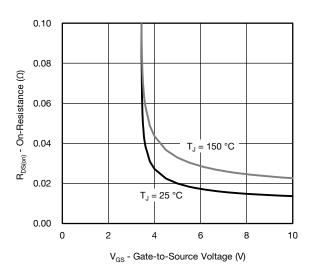




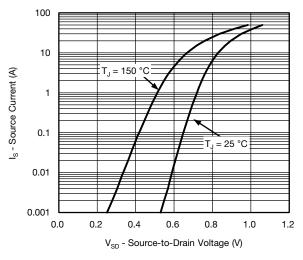
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



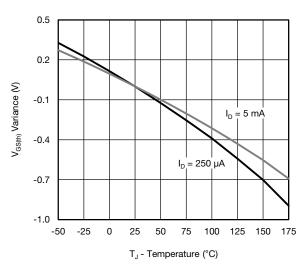
## On-Resistance vs. Junction Temperature



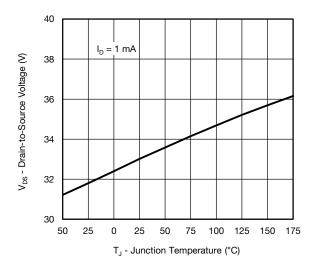
On-Resistance vs. Gate-to-Source Voltage



#### **Source Drain Diode Forward Voltage**



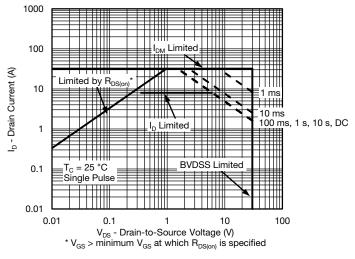
### Threshold Voltage



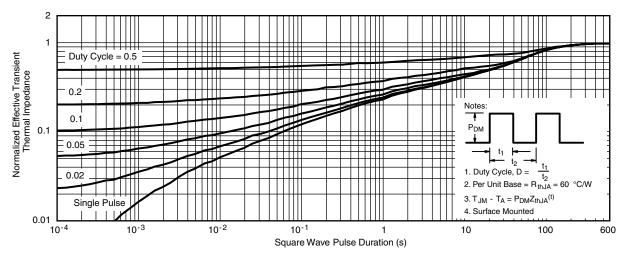
Drain Source Breakdown vs. Junction Temperature



# **THERMAL RATINGS** ( $T_A = 25$ °C, unless otherwise noted)



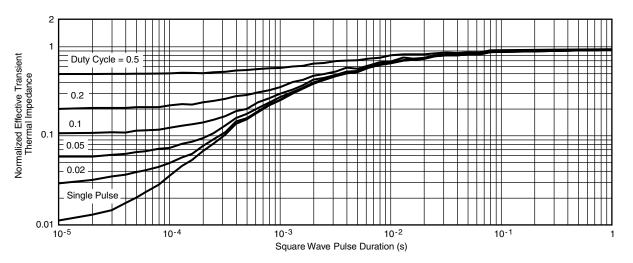
**Safe Operating Area** 



Normalized Thermal Transient Impedance, Junction-to-Ambient



# THERMAL RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction-to-Case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg262832">www.vishay.com/ppg262832</a>.



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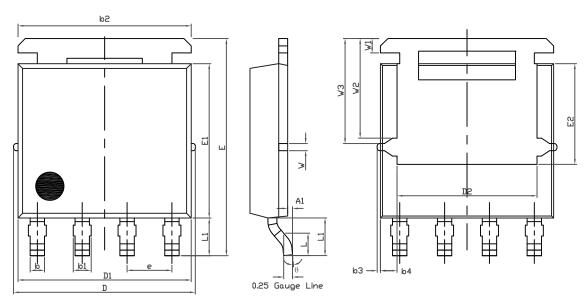
REVISION	HISTORY a	
REVISION	DATE	DESCRIPTION OF CHANGE
В	04-Aug-15	Revised R <sub>g</sub> minimum limit

#### Note

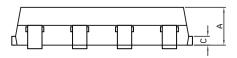
a. As of April 2014

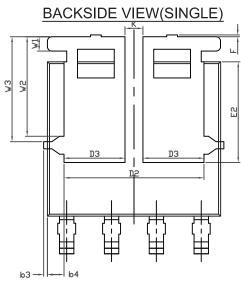


# PowerPAK® SO-8L Case Outline 2



**TOPSIDE VIEW** 





BACKSIDE VIEW(DUAL)



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DIM	MILLIMETERS			INCHES			
DIM.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
Α	1.00	1.07	1.14	0.039	0.042	0.045	
A1	0.00	-	0.127	0.00	-	0.005	
b	0.33	0.41	0.48	0.013	0.016	0.019	
b1	0.44	0.51	0.58	0.017	0.020	0.023	
b2	4.80	4.90	5.00	0.189	0.193	0.197	
b3		0.094			0.004		
b4		0.47			0.019		
С	0.20	0.25	0.30	0.008	0.010	0.012	
D	5.00	5.13	5.25	0.197	0.202	0.207	
D1	4.80	4.90	5.00	0.189	0.193	0.197	
D2	3.86	3.96	4.06	0.152	0.156	0.160	
D3	1.63	1.73	1.83	0.064	0.068	0.072	
е		1.27 BSC		0.050 BSC			
Е	6.05	6.15	6.25	0.238	0.242	0.246	
E1	4.27	4.37	4.47	0.168	0.172	0.176	
E2	2.75	2.85	2.95	0.108	0.112	0.116	
F	-	-	0.15	-	-	0.006	
L	0.62	0.72	0.82	0.024	0.028	0.032	
L1	0.92	1.07	1.22	0.036	0.042	0.048	
K		0.51			0.020		
W		0.23			0.009		
W1		0.41			0.016		
W2	2.82			0.111			
W3		2.96			0.117		
q	0°	-	10°	0°	-	10°	

ECN: S19-0643-Rev. B, 05-Aug-2019

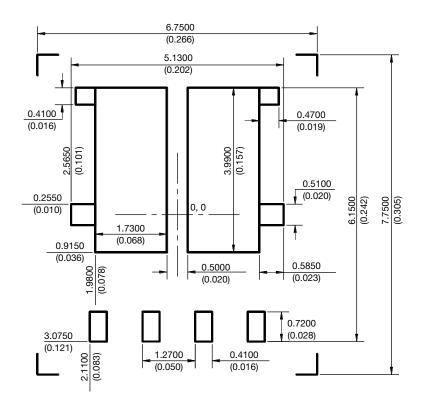
DWG: 6044

### Note

• Millimeters will gover

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### RECOMMENDED MINIMUM PAD FOR PowerPAK® SO-8L DUAL



Recommended Minimum Pads Dimensions in mm (inches) Keep-out 6.75 (0.266) x 7.75 (0.305)



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